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Please amend the paragraph on page 2, lines 20-25 as follows:

Q2 Referring to FIG. 2A and FIG. 2B, the TBGA package is constructed on a heat sink 10 and a tape 20 adhered to the heat sink 10 by means of an adhesive layer 21. Further, the tape 20 is formed with a via hole 22 to expose a selected part of the heat sink 10. To allow ground-ball attachment, a ring-shaped ground-ball 31 is formed over the tape 20 and around the via hole 22; and a solder mask 40 is formed over the tape 20 to mask all the areas on the tape 20 other than the inner part of the ground-ball pad 31.

Please amend the paragraph on page 6, lines 12-17 as follows:

Q3 As shown in FIG. 3B, it is a characteristic feature of the invention that the ring-shaped ground-ball pad 131 is formed with a plurality of air vents 131a spaced substantially at equal radial intervals around the ground-ball pad 131, and the air vents 131a are cut all the way into the tape 120 until reaching the bottom surface of the heat sink 110. In this embodiment, the air vents 131a are rectangularly shaped in cross section and spaced at 180° radial intervals around the ring-shaped ground-ball pad 131.

Please amend the last paragraph on page 6 as follows:

Q4 In the embodiment of FIG. 3B, the ground-ball pad 131 includes two air vents 131a which are each substantially rectangularly-shaped in cross section and are arranged at 180° intervals on the periphery of the ground-ball pad 131.

Please amend the first paragraph on page 7 as follows:

FIGs. 4A-4C are schematic diagrams showing various other embodiments of the ring-shaped ground-ball pad 131. In the embodiment of FIG. 4A, the ring-shaped ground-ball pad 131 is formed with two air vents 131b which are triangularly shaped in cross section and spaced at 180° radial intervals around the ring-shaped ground-ball pad 131. In the embodiment of FIG.